



(12) **United States Design Patent**  
**Akazawa et al.**

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(54) **ELASTIC MEMBRANE FOR SEMICONDUCTOR WAFER POLISHING APPARATUS**  
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(73) Assignee: **EBARA CORPORATION**, Tokyo (JP)  
(\*\*) Term: **15 Years**

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(58) **Field of Classification Search**  
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D15/144.1, 199  
CPC ..... C23C 16/4582; C23C 16/4583; C23C  
16/4585; C23C 16/4586; C30B 25/10;  
H01L 21/68  
See application file for complete search history.

(57) **CLAIM**

The ornamental design for an elastic membrane for semiconductor wafer polishing apparatus, as shown and described.

(56) **References Cited**

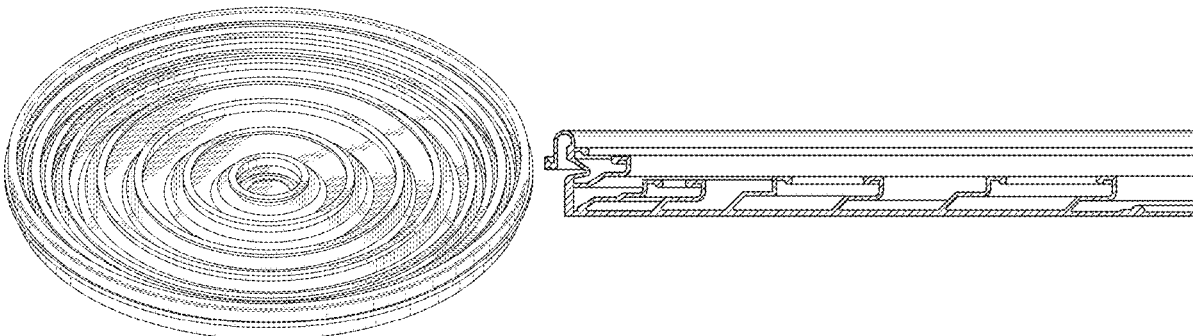
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**DESCRIPTION**

FIG. 1 is a top perspective view of an elastic membrane for semiconductor wafer polishing apparatus showing our new design;  
FIG. 2 is a bottom perspective view thereof;  
FIG. 3 is a top view thereof;  
FIG. 4 is a bottom view thereof;  
FIG. 5 is a front view thereof, the rear view being identical;  
FIG. 6 is a right-side view thereof, the left-side view being identical;  
FIG. 7 is an enlarged cross-sectional end view taken along line 7-7 in FIG. 3 thereof; and,  
FIG. 8 is an enlarged detail view of section 8 in FIG. 7 thereof.

**1 Claim, 6 Drawing Sheets**



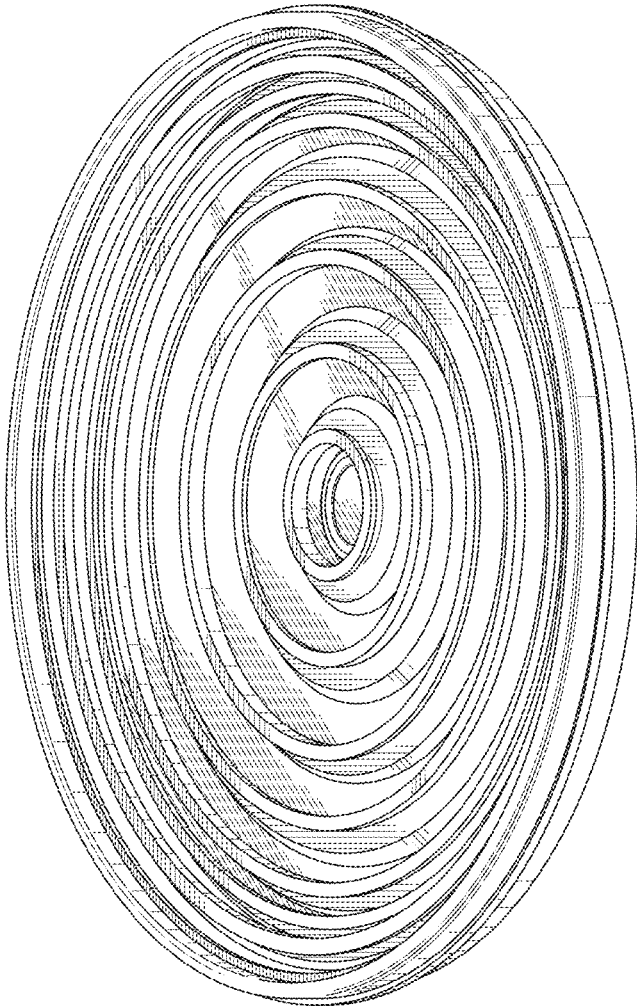


Fig. 1

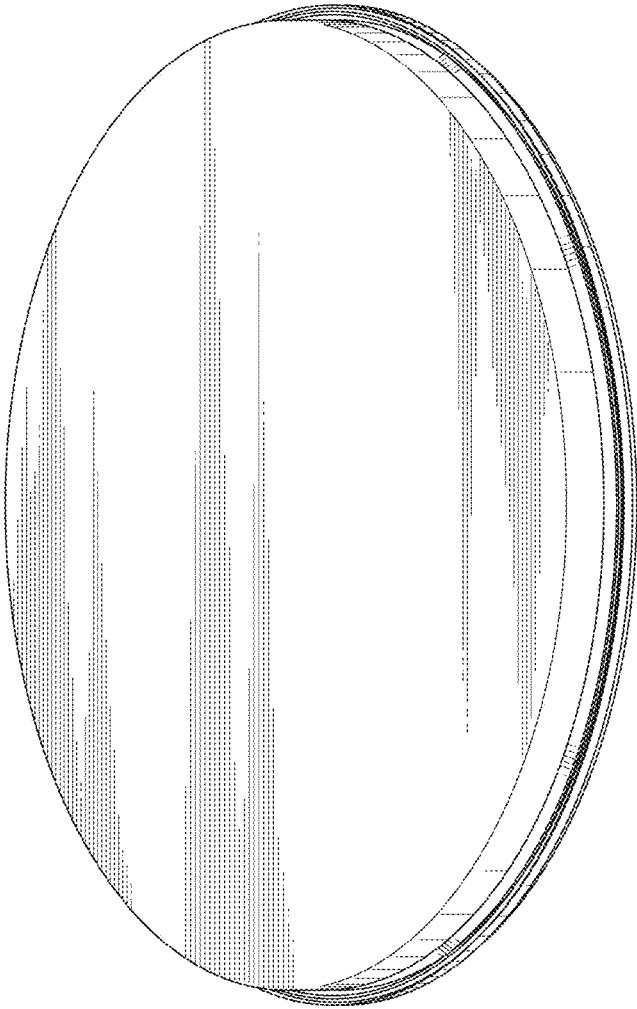


Fig.2

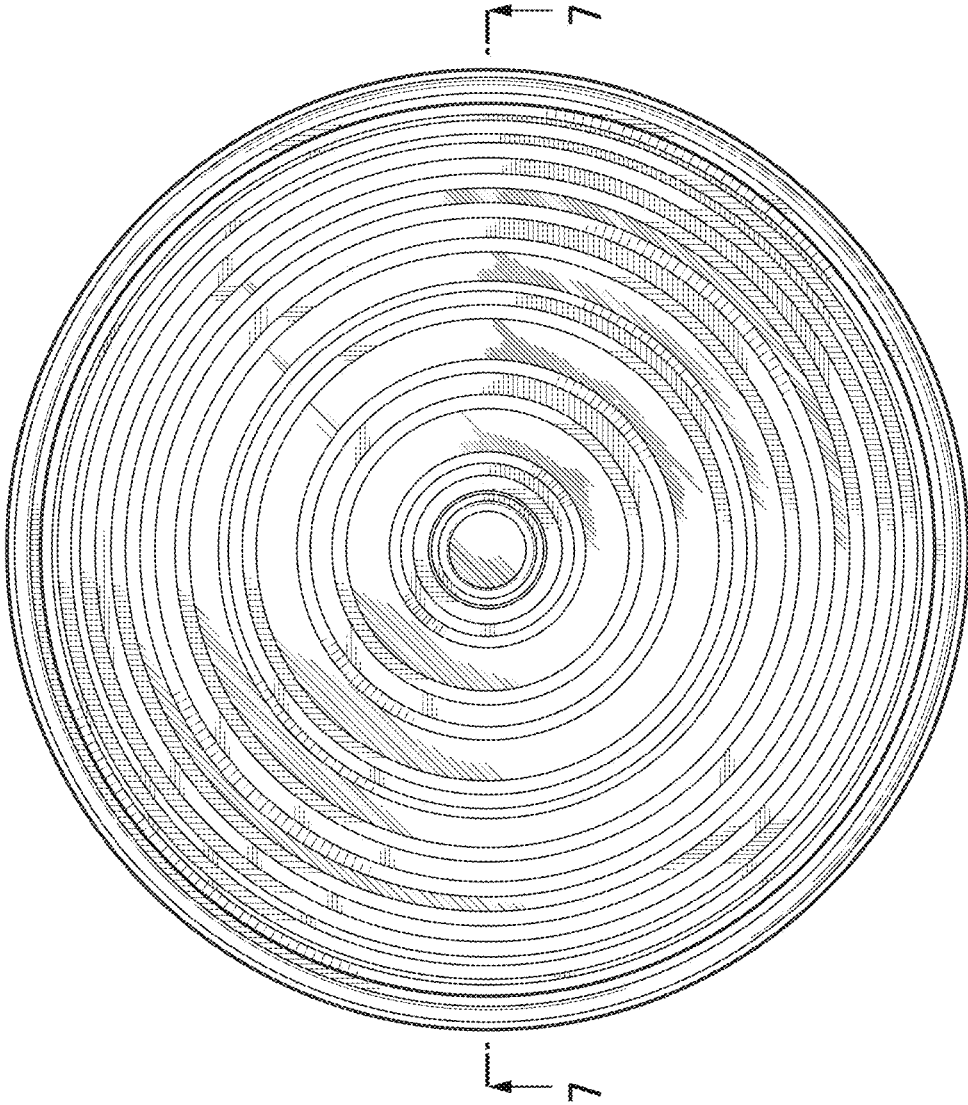


Fig.3

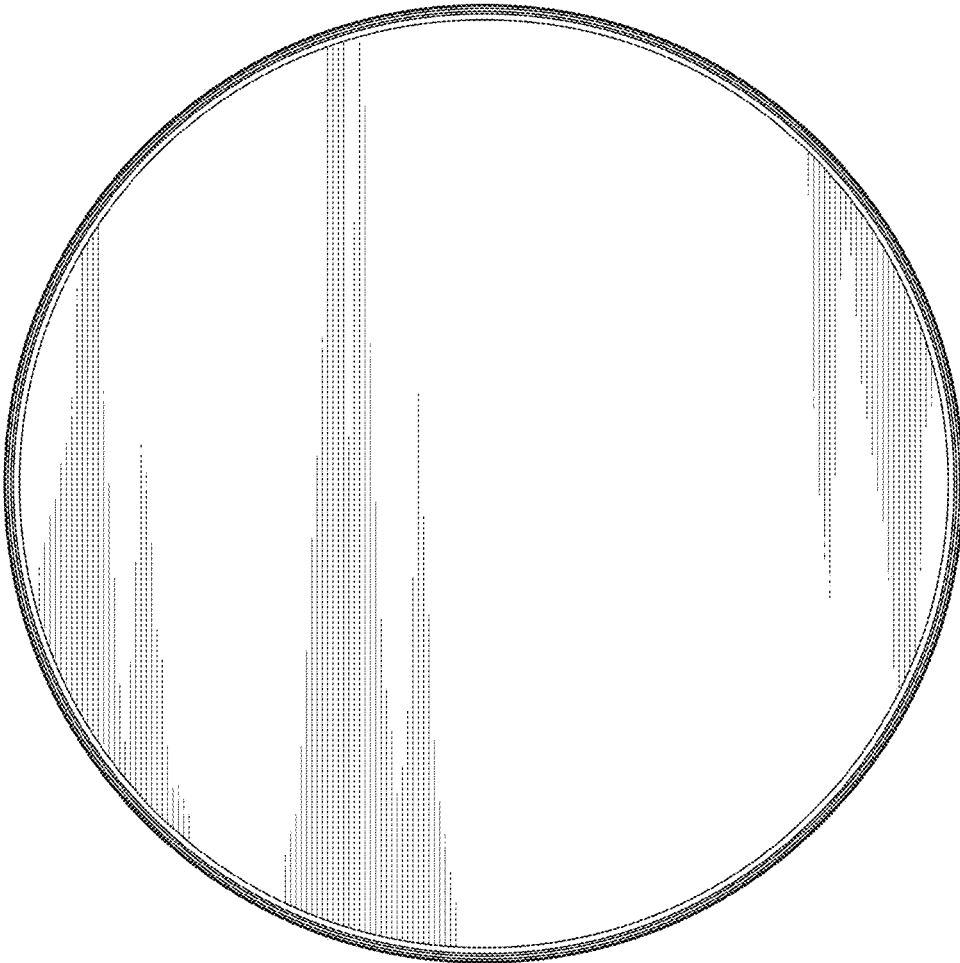


Fig.4

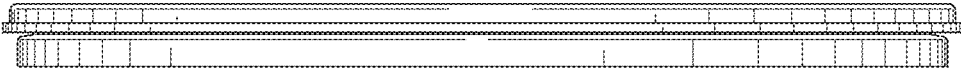


Fig.5

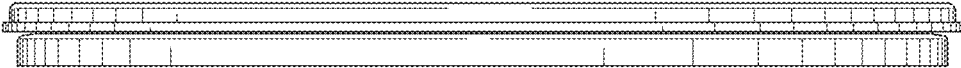


Fig.6

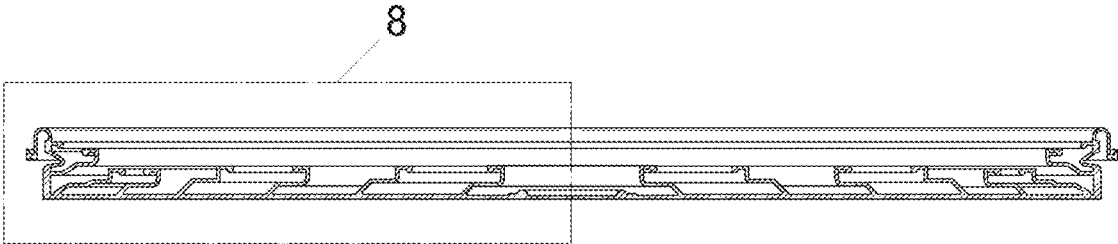


Fig.7

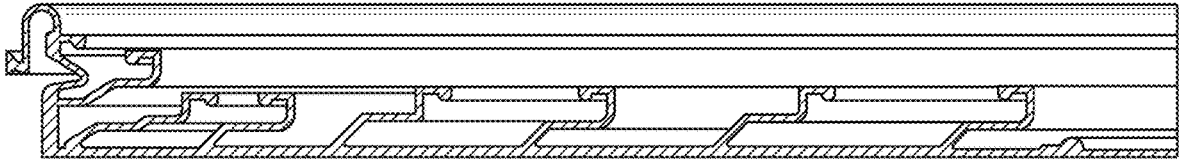


Fig.8